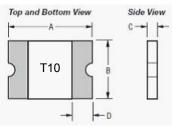


# **Product Introduction**

## 1. Product Dimensions & Outline Drawing & marking (Unit:mm)



Manufacturer's Trademark Part Identification

Model	A		F	3	C	D	
	Min.	Max.	Min.	Max.	Min.	Max.	Min.
NSMD110	3.00	3.40	1.40	1.80	0.80	1.20	0.25

#### 2. Electrical Properties

	Model	I <sub>H</sub> (A)	I <sub>T</sub> (A)	V <sub>max</sub> (V)	I <sub>max</sub> (A)	(Max tim	ne to trip) (S)	Pd <sub>typ</sub> (W)	$R_{min} (\Omega)$	$R1_{max}$ $(\Omega)$
1	NSMD110	1.00	2.00	13.2	100	8.00	0.10	0.60	0.060	0.280

I<sub>H</sub>: Holding Current: maximum current at which the device will not trip in 25 °C still air.

I<sub>T</sub>: Tripping Current minimum current at which the device will trip in 25°C still air.

V<sub>max</sub>: Maximum voltage device can withstand without damage at rated current.

I max: Maximum fault current device can withstand without damage at rated voltage.

T trip: Maximum time to trip(s) at assigned current.

Pd<sub>typ</sub>: Rated working power.

R<sub>min</sub>: Minimum resistance of device prior to trip at 25°C.

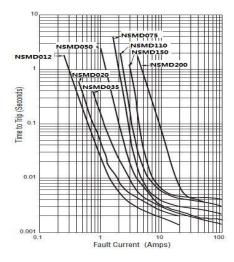
R<sub>max</sub>: Maximum resistance of device prior to trip at 25°C.

R1  $_{\rm max}$ : Maximum resistance of device is measured one hours post reflow at 25  $^{\circ}$ C.

#### 3. Thermal Derating Chart – Ihold (Amps)

Model	Ambient Operating Temperature									
	-40°C	-20°C	0℃	25℃	40℃	50°C	60°C	70°C	85℃	
NSMD110	1.60	1.40	1.30	1.00	0.90	0.80	0.75	0.70	0.60	

### 4. Typical time to trip at 25℃



◆ Time to Trip curves represent typical performance of a device in a simulated application environment. Actual performance in specific customer applications may differ from these values due to the influence of other variables.